

ROITHNER LASERTECHNIK GmbH

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SMB1W-470



TECHNICAL DATA

High Power LED, SMD

InGaN

SMB1W-470 are InGaN High Power LEDs mounted on a cooper heat sink with a 5x5 mm SMD package and molded with epoxy resin. On forward bias, it emits a radiation of typical 110 mW at a peak wavelength of 470 nm.

Specifications

Structure: InGaN, 1W high power chip

• Peak Wavelength: typ. 470 nm

Optical Output Power: typ. 100 mW

Package

SMD, PPA resin

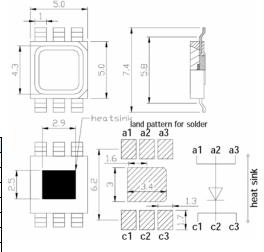
Lead frame die: silver plated on copper

Lens: epoxy resin

Absolute Maximum Ratings (T_a =25°C)

Item	Symbol	Value	Unit
Power Dissipation	P_{D}	1400	mW
Forward Current	I _F	350	mA
Pulse Forward Current *1	I _{FP}	700	mA
Reverse Voltage	V_R	5	V
Thermal Resistance	R _{th}	10	K/W
Operating Temperature	T _{opr}	-30 +85	°C
Storage Temperature	T _{stq}	-30 +100	°C
Soldering Temperature *2	T _{sol}	255	°C
.1			

 $^{^{*1}}$ duty = 1%, pulse width = 10 µs *2 must be completed within 5 seconds



(Unit: mm)

Electro-Optical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	V _F	$I_F = 200 \text{ mA}$	-	3.4	4.0	V
		$I_F = 350 \text{ mA}$	-	3.6	4.2	
Pulsed Forward Current	V_{FP}	$I_{FP} = 700 \text{ mA}$	-	4.0	4.8	V
Total Radiated Power	Po	$I_F = 200 \text{ mA}$	-	110	-	- mW
		$I_{FP} = 700 \text{ mA}$	-	360	-	
Brightness	I_{V}	$I_F = 350 \text{ mA}$	-	3800	-	mcd
Peak Wavelength	λ_{P}	$I_F = 50 \text{ mA}$	-	470	-	nm
Half Width	Δλ	$I_F = 50 \text{ mA}$	-	17	-	nm
Viewing Half Angle	Θ _{1/2}	$I_F = 50 \text{ mA}$	-	±60	-	deg.

Total Radiated Power is measured by S3584-08

Notes

- Do not view directly into the emitting area of the LED during operation!
- The above specifications are for reference purpose only and subjected to change without prior notice.

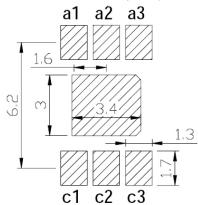


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Recommended Land Layout (Unit: mm)

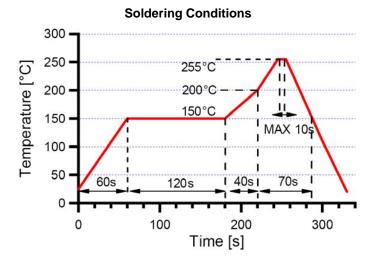


1. Soldering Conditions

DO NOT apply any stress to the lead particularly when heat.

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- After soldering the LEDs should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.



2. Static Electricity

- The LEDs are very sensitive to Static Electricity and surge voltage. So it is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.
- All devices, equipment and machinery must be grounded properly. It is recommended that precautions should be taken against surge voltage to the equipment that mounts the LEDs.

